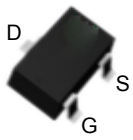
Features

- -20V/-5A,
  $R_{DS(ON)}$=32mΩ (typ.) @ V_{GS}=-4.5V
  $R_{DS(ON)}$=42mΩ (typ.) @ V_{GS}=-2.5V
  $R_{DS(ON)}$=52mΩ (typ.) @ V_{GS}=-1.8V
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

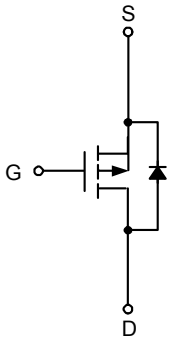
Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems

Pin Description



Top View of SOT-23



P-Channel MOSFET

Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Symbol	Parameter		Rating	Unit
V_{DSS}	Drain-Source Voltage		-20	V
V_{GSS}	Gate-Source Voltage		±8	
I_D*	Continuous Drain Current	V_{GS}=-4.5V	-5	A
I_{DM}*	Pulsed Drain Current		-15	
I_S*	Diode Continuous Forward Current		-5	A
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	
P_D*	Maximum Power Dissipation	T_A=25°C	0.83	W
		T_A=100°C	0.3	
$R_{\theta JA}$*	Thermal Resistance-Junction to Ambient		150	°C/W

Note : *Surface Mounted on 1in^2 pad area, t ≤ 10sec.

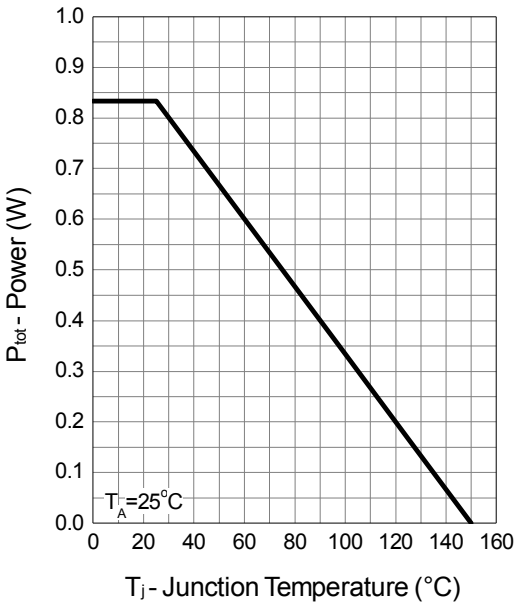
Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=-250μA	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-16V, V_{GS}=0V	-	-	-1	μA
		T_J=85°C	-	-	-30	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=-250μA	-0.5	-0.6	-1	V
I_{GSS}	Gate Leakage Current	V_{GS}=±10V, V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$ [a]	Drain-Source On-state Resistance	V_{GS}=-4.5V, I_{DS}=-6A	-	32	42	mΩ
		V_{GS}=-2.5V, I_{DS}=-4.5A	-	42	60	
		V_{GS}=-1.8V, I_{DS}=-3A	-	52	70	
V_{SD} [a]	Diode Forward Voltage	I_{SD}=-0.5A, V_{GS}=0V	-	-0.75	-1.3	V
Gate Charge Characteristics [b]						
Q_g	Total Gate Charge	V_{DS}=-10V, V_{GS}=-4.5V, I_{DS}=-4A	-	12	16	nC
Q_{gs}	Gate-Source Charge		-	2.1	-	
Q_{gd}	Gate-Drain Charge		-	2.9	-	
Dynamic Characteristics [b]						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1MHz	-	8	-	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-15V, Frequency=1.0MHz	-	1135	-	pF
C_{oss}	Output Capacitance		-	200	-	
C_{rss}	Reverse Transfer Capacitance		-	110	-	
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=-10V, R_L=10Ω, I_{DS}=-1A, V_{GEN}=-4.5V, R_G=6Ω	-	6	12	ns
T_r	Turn-on Rise Time		-	7	14	
$t_{d(OFF)}$	Turn-off Delay Time		-	72	131	
T_f	Turn-off Fall Time		-	45	82	

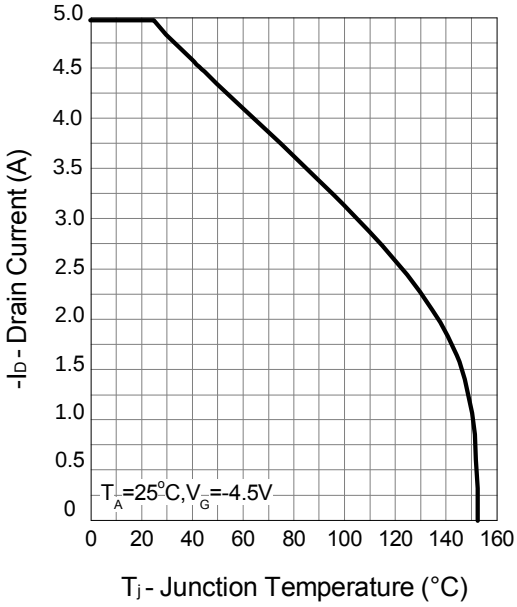
Note a : Pulse test ; pulse width≤300μs, duty cycle≤2%.
Note b : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

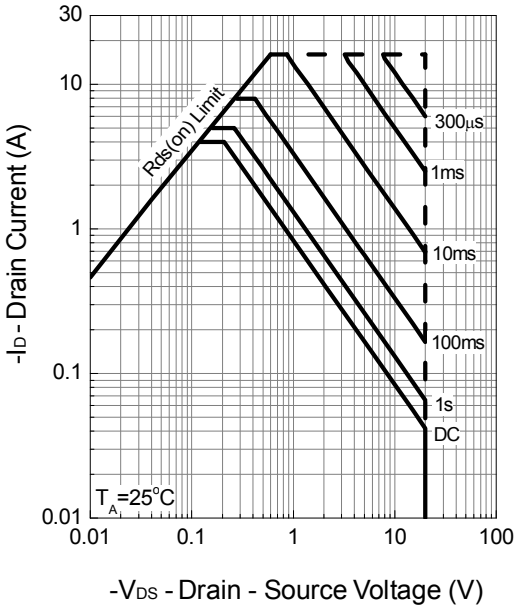
Power Dissipation



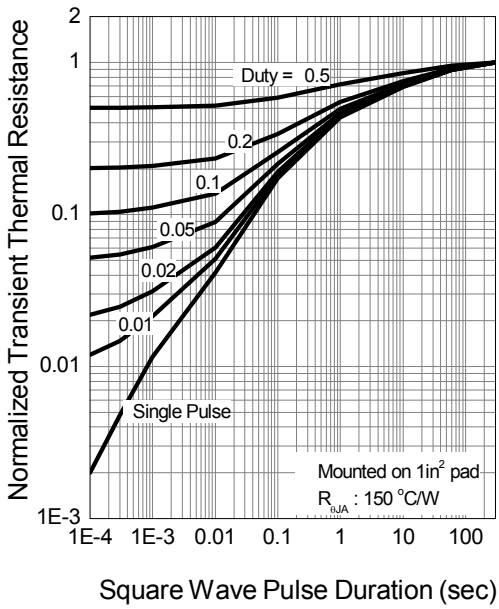
Drain Current



Safe Operation Area

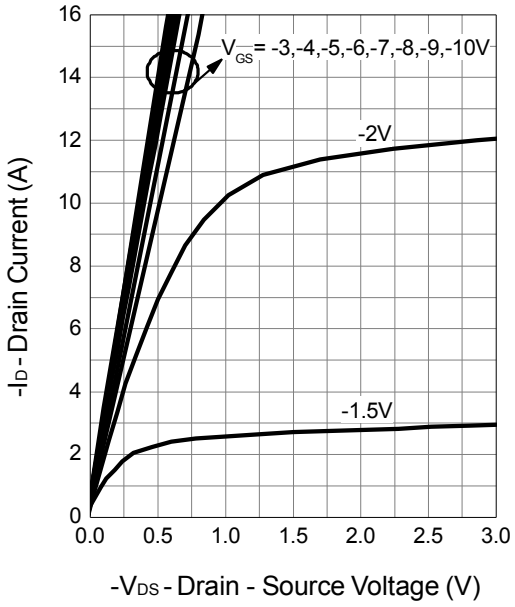


Thermal Transient Impedance

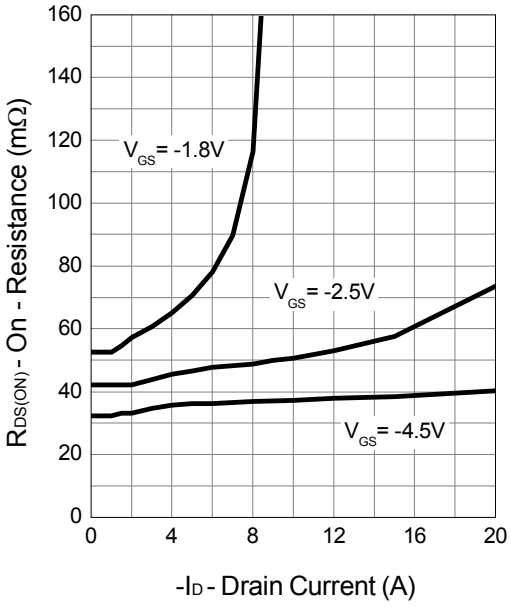


Typical Operating Characteristics (Cont.)

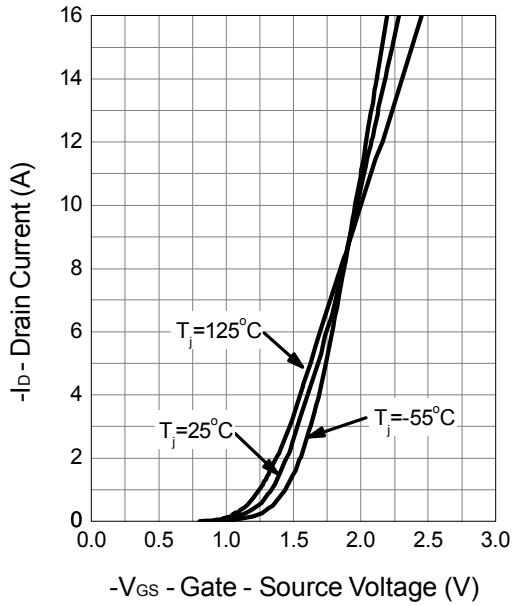
Output Characteristics



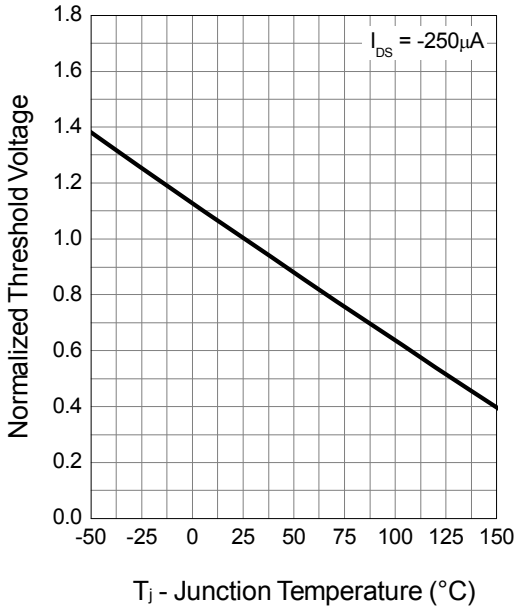
Drain-Source On Resistance



Transfer Characteristics

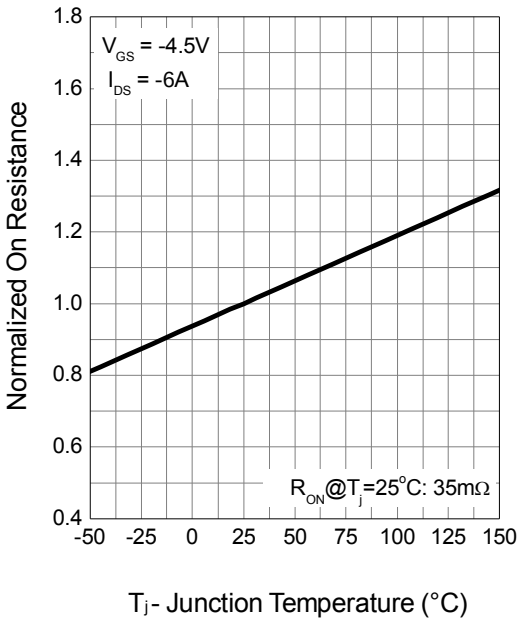


Gate Threshold Voltage

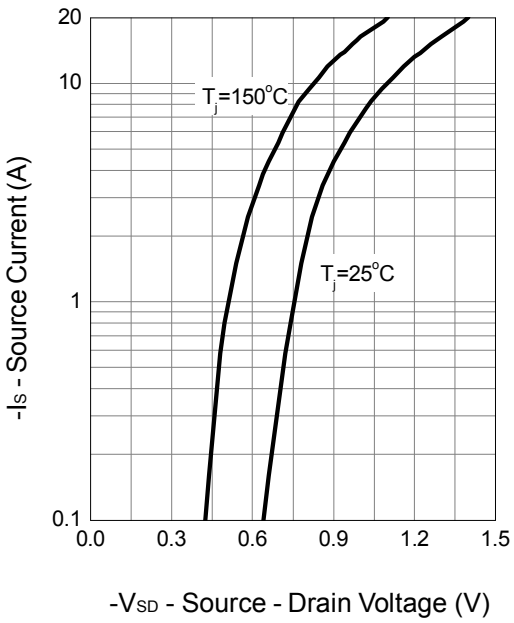


Typical Operating Characteristics (Cont.)

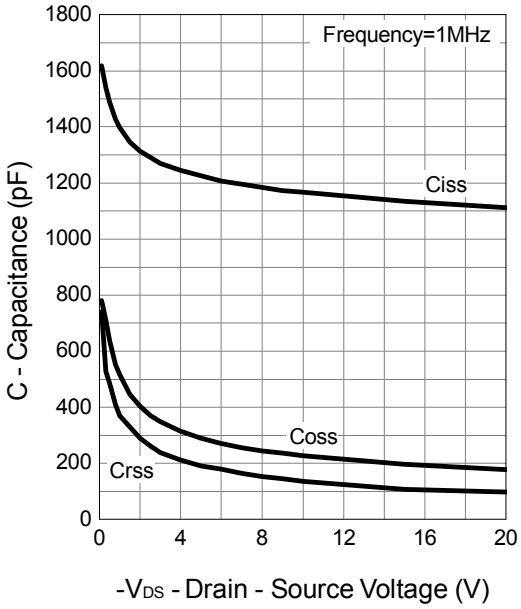
Drain-Source On Resistance



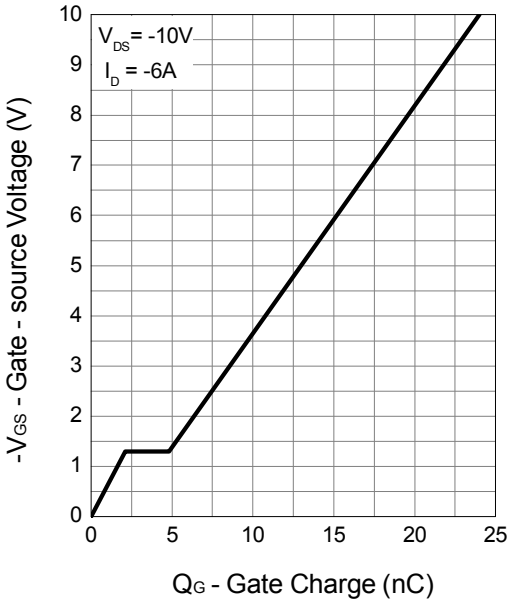
Source-Drain Diode Forward



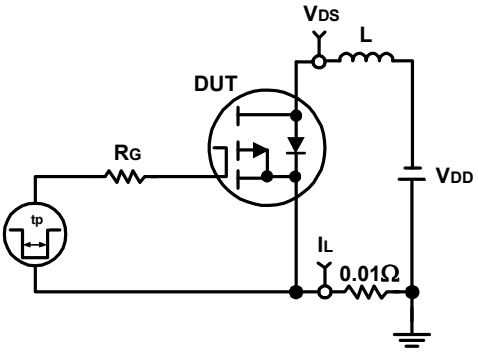
Capacitance

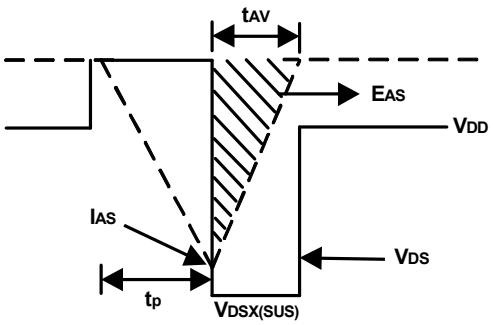


Gate Charge

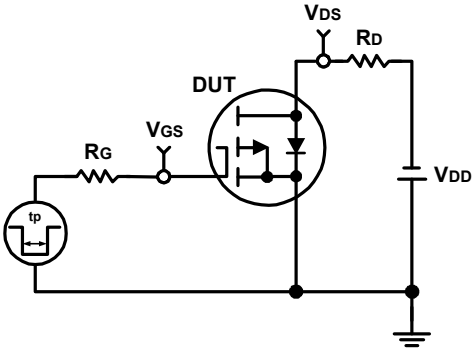


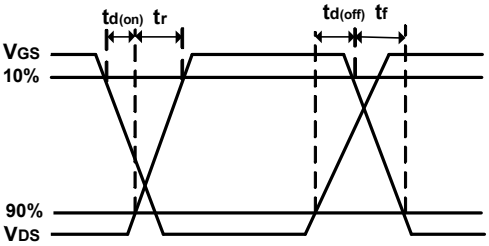
Avalanche Test Circuit and Waveforms





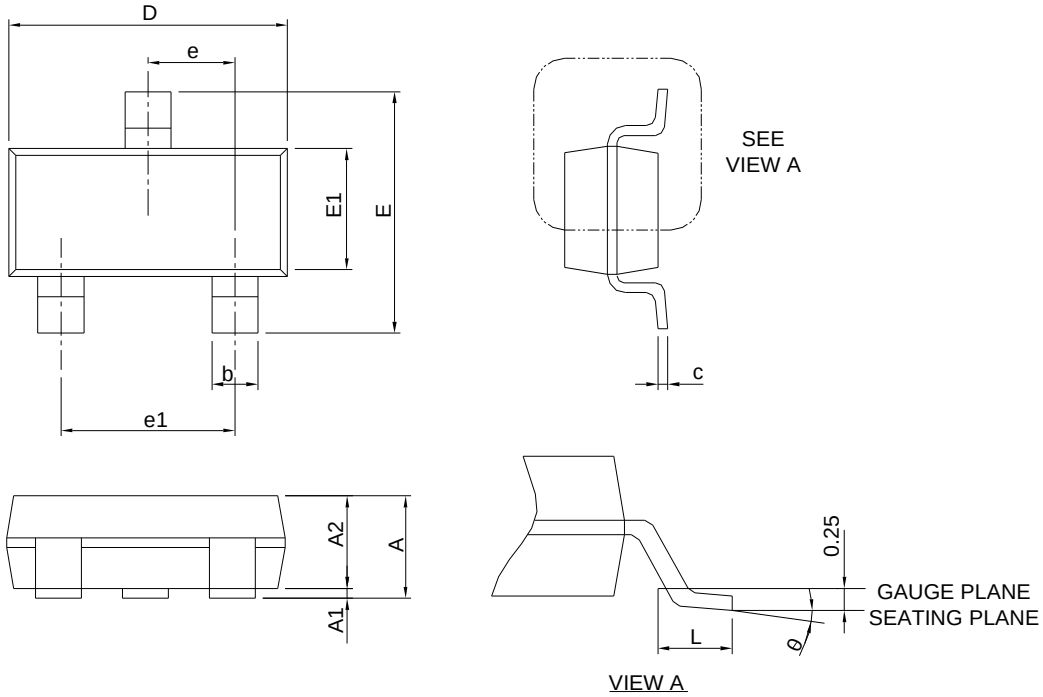
Switching Time Test Circuit and Waveforms





Package Information

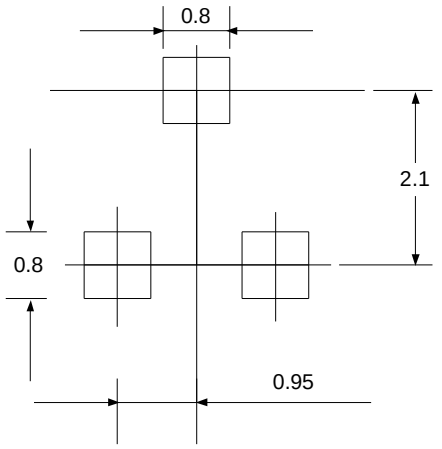
SOT-23



SYMBOL	SOT-23			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	1.20	-	0.047
A1	0.00	0.10	0.000	0.004
A2	0.90	1.10	0.035	0.043
b	0.30	0.50	0.012	0.020
c	0.08	0.22	0.003	0.009
D	2.70	3.10	0.106	0.122
E	2.20	2.60	0.086	0.102
E1	1.20	1.40	0.047	0.055
e	0.95 BSC		0.037 BSC	
e1	1.90 BSC		0.075 BSC	
L	0.30	0.60	0.012	0.024
θ	0 °	8 °	0 °	8 °

Note : Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.

RECOMMENDED LAND PATTERN



UNIT: mm